

RS1G201AT

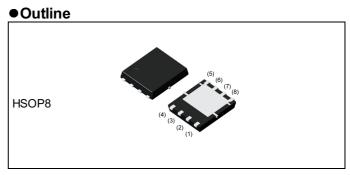
# Pch -40V -78A Power MOSFET

V <sub>DSS</sub>	-40V
R <sub>DS(on)</sub> (Max.)	5.2mΩ
I <sub>D</sub>	±78A
P <sub>D</sub>	40W

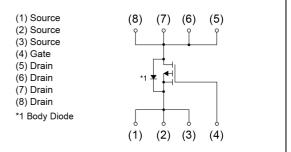
## Features

Application
 Load Switching

- 1) Low on resistance
- 2) Small Surface Mount Package (HSOP8)
- 3) Pb-free plating ; RoHS compliant



## ●Inner circuit



# Packaging specifications

Туре	Packing	Embossed Tape
	Reel size (mm)	330
	Tape width (mm)	12
	Quantity (pcs)	2500
	Taping code	TB1
	Marking	RS1G201AT

#### • Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Paramete	Symbol	Value	Unit		
Drain - Source voltage		V <sub>DSS</sub>	-40	V	
Continuous dusis sumont	$T_c = 25^{\circ}C$	۱ <sub>D</sub> *1	±78	А	
Continuous drain current	$T_a = 25^{\circ}C$	I <sub>D</sub>	±20	А	
Pulsed drain current	I <sub>DP</sub> *2	±80	Α		
Gate - Source voltage		V <sub>GSS</sub>	±20	V	
Avalanche current, single pulse		I <sub>AS</sub> *3	-20	Α	
Avalanche energy, single pulse		E <sub>AS</sub> *3	31	mJ	
		P <sub>D</sub> <sup>*1</sup>	40	W	
Power dissipation		P <sub>D</sub> <sup>*4</sup>	3.0	W	
Junction temperature		Tj	150	°C	
Operating junction and storage temperature range		T <sub>stg</sub>	-55 to +150	C°	

## Thermal resistance

Deremeter	Sumbol	Values			Linit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	-	3.1	°C/W
Thermal resistance, junction - ambient	$R_{thJA}^{*4}$	-	-	41.7	°C/W

# •Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Currence of	Conditions	Values			Linit	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = -1mA$		-40	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{i}} I_{D} = -1mA$ referenced to 25°C		-22	-	mV/°C	
Zero gate voltage drain current	$I_{DSS}$ $V_{DS}$ = -40V, $V_{GS}$ = 0V		-	-	-1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$I_{GSS}$ $V_{GS} = \pm 20V, V_{DS} = 0V$		-	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -1mA$	-1.0	-	-2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$			3.7	-	mV/°C	
Static drain - source	D *5	V <sub>GS</sub> = -10V, I <sub>D</sub> = -20A	-	4.2	5.2		
on - state resistance	${\sf R}_{\sf DS(on)}^{*5}$	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -20A	-	5.2	6.5	mΩ	
Gate resistance	R <sub>G</sub>	R <sub>G</sub> f=1MHz, open drain		4.6	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  * <sup>5</sup>			-	-	S	

\*1 T<sub>c</sub> = 25°C, Limited only by maximum temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

\*3 L  $\simeq$  0.1mH, V\_{DD} = -20V, R\_G = 25 $\Omega$ , Starting T\_j = 25°C Fig.3-1,3-2

- \*4 Mounted on a Cu board (40×40×0.8mm)
- \*5 Pulsed



# •Electrical characteristics ( $T_a = 25^{\circ}C$ )

Deremeter	Cumph of	Conditions		Linit			
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	6890	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = -20V	-	770	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	590	-		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq -20V, V_{GS} = -10V$	-	24	-		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = -10A	-	98	-		
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L \simeq 2\Omega$	-	330	-	ns	
Fall time	t <sub>f</sub> *5	R <sub>G</sub> = 10Ω	-	250	-		

# • Gate charge characteristics (T<sub>a</sub> = 25°C)

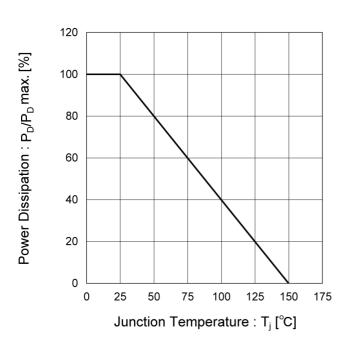
Deremeter	Sumbol	Conditions		Values			l lait	
Parameter	Symbol Conditions		UNS	Min.	Тур.	Max.	Unit	
Total gate charge	Qg <sup>*5</sup>	V <sub>DD</sub> ≃ -20V	V <sub>GS</sub> = -10V	-	130	-		
				-	62	-		
Gate - Source charge	$Q_{gs}^{*5}$	I <sub>D</sub> = -20A	V <sub>GS</sub> = -4.5V	-	24	-	nC	
Gate - Drain charge	Q <sub>gd</sub> *5			-	17	-		

# •Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Deremeter	Symbol Conditions			Unit		
Parameter			Min.	Тур.	Max.	Unit
Continuous forward current	I <sub>S</sub>	T <sub>a</sub> = 25℃	-	-	-2.5	А
Pulse forward current	I <sub>SP</sub> *2	$T_a = 25 C$	-	-	-80	А
Forward voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = -2.5A	-	-	-1.2	V
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = -20A, V <sub>GS</sub> =0V	-	34	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/µs	-	33	-	nC



# Electrical characteristic curves



# Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

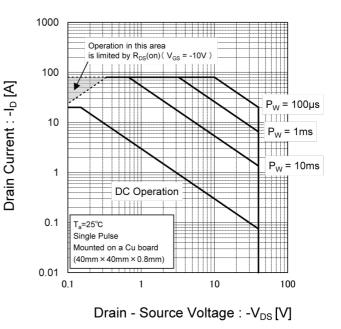
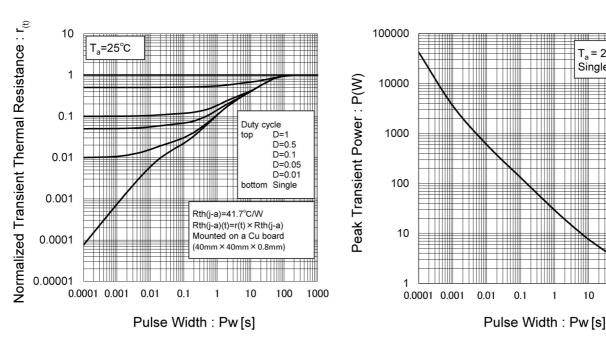


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power Dissipation

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10

100

1000

T<sub>a</sub> = 25°C Single Pulse

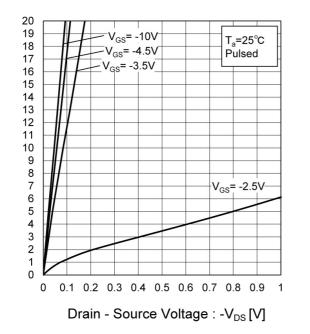


Fig.7 Breakdown Voltage vs.

Junction Temperature

Fig.5 Typical Output Characteristics(I)

Fig.6 Typical Output Characteristics(II)

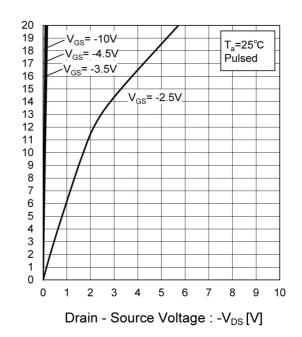
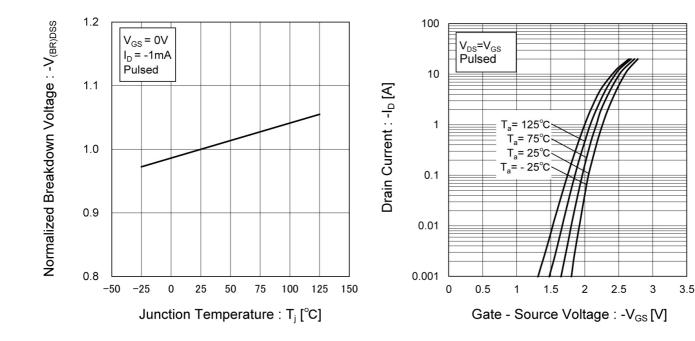


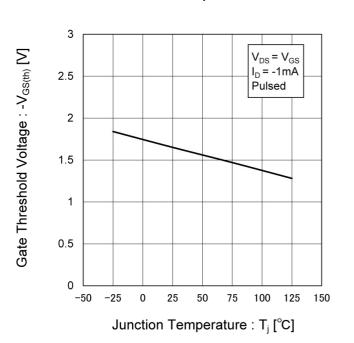
Fig.8 Typical Transfer Characteristics

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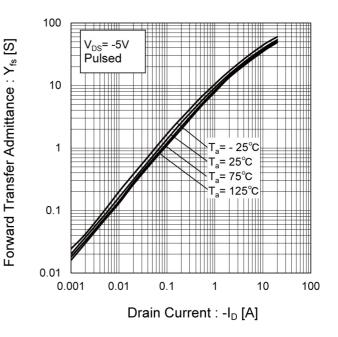


Drain Current : -I<sub>D</sub> [A]

# • Electrical characteristic curves



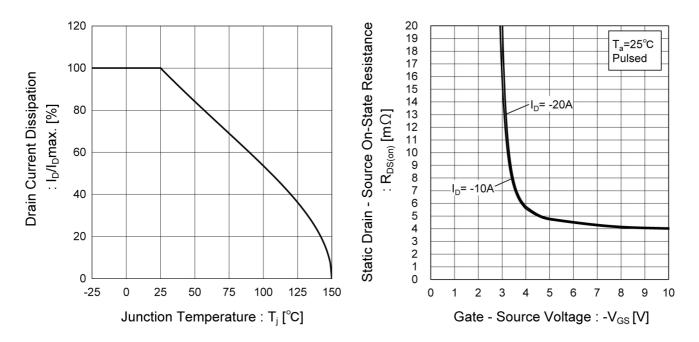
### Fig.9 Gate Threshold Voltage vs. Junction Temperature



# Fig.10 Forward Transfer Admittance vs. Drain Current

Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage





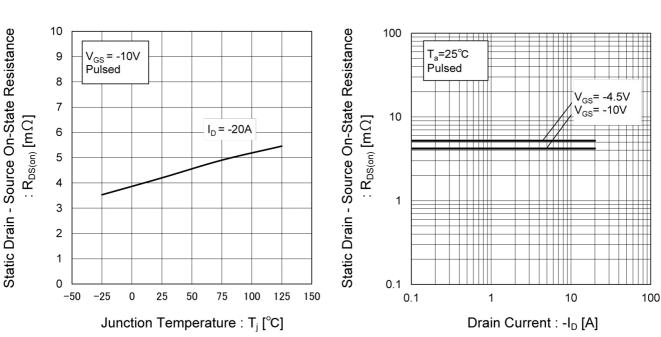
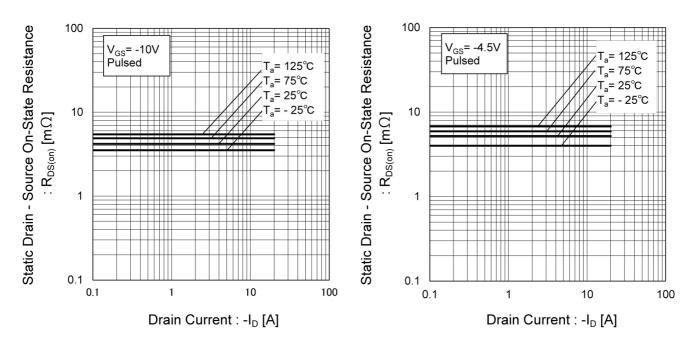


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

Fig.15 Static Drain - Source On - State
Resistance vs. Drain Current (II)

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)



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# • Electrical characteristic curves

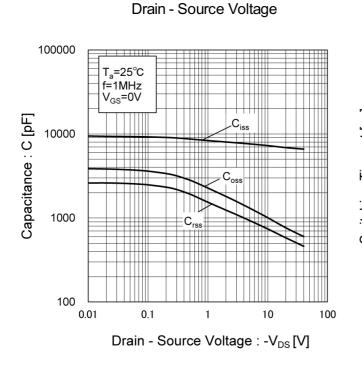


Fig.17 Typical Capacitances vs.

## Fig.18 Switching Characteristics

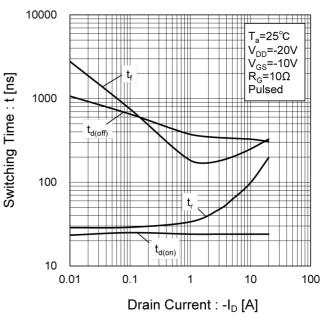


Fig.19 Typical Gate Charge

Gate - Source Voltage : -V<sub>GS</sub> [V]

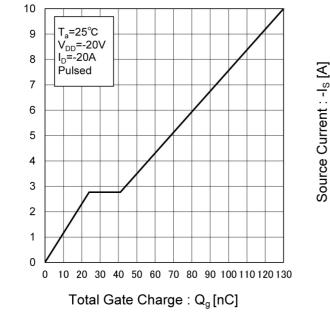
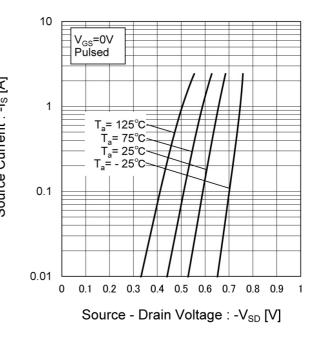


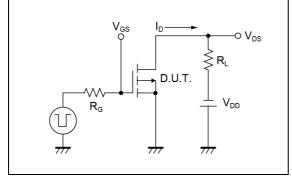
Fig.20 Source Current vs. Source Drain Voltage



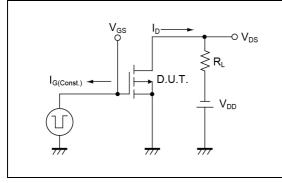


# Measurement circuits

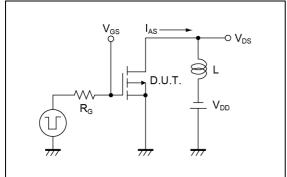
Fig.1-1 Switching Time Measurement Circuit



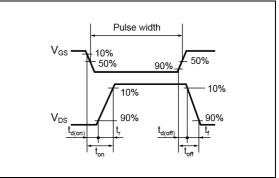
#### Fig.2-1 Gate Charge Measurement Circuit



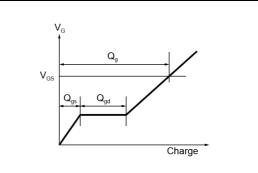
#### Fig.3-1 Avalanche Measurement Circuit



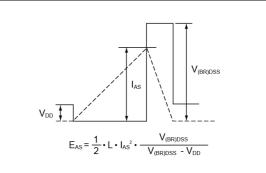
#### Fig.1-2 Switching Waveforms



#### Fig.2-2 Gate Charge Waveform



#### Fig.3-2 Avalanche Waveform

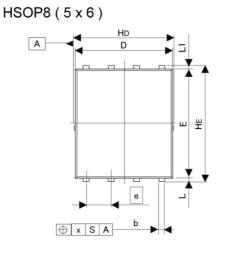


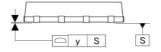
# Notice

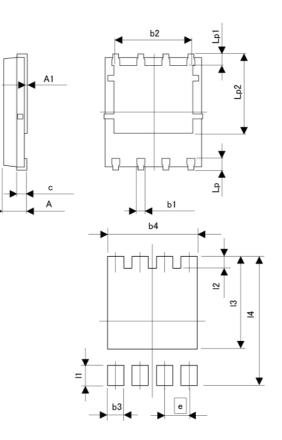
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.



### Dimensions







Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
A	0.90	1.10	0.035	0.043
A1	0.00	0.05	0.000	0.002
b	0.24	0.42	0.009	0.017
b1	0.29	0.49	0.011	0.019
b2	3.81	4.21	0.150	0.166
С	0.20	0.30	0.008	0.012
D	4.80	5.00	0.189	0.197
E	5.60	5.80	0.220	0.228
е	1.	27	0.0	50
HD	4.90	5.10	0.193	0.201
HE	5.90	6.10	0.232	0.240
L	0.07	0.25	0.003	0.010
L1	0.07	0.25	0.003	0.010
Lp	0.50	0.70	0.020	0.028
Lp1	0.52	0.72	0.020	0.028
Lp2	3.92	4.32	0.154	0.170
x	-	0.10	-	0.004
у	-	0.10	-	0.004
DIM		TERS		HES
Divi	MIN	MAX	MIN	MAX
b3	-	0.59	-	0.023
b4	-	4.21	-	0.166
1	-	0.80		0.031
12	-	0.82	-	0.032
13	-	4.32	-	0.170
14	-	6.10	-	0.240

Dimension in mm/inches



# Notice

#### Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (<sup>Note 1)</sup>, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications
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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSI	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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When disposing Products please dispose them properly using an authorized industry waste company.

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